

Copper

SLOTOCOUP SF 50

Copper SLOTOCOUP SF 50 is applied for the production of printed circuit boards (PCBs) for pattern plating (L/S < 50/50) as well as for through hole plating of Blind Micro Vias (BMV) with a very good filling capacity. Internal-, intermediate- as well as external layers can be processed with this process. Additionally, Copper SLOTOCOUP SF 50 can completely fill BMV in one process step and copper plating of through holes at the same time. Copper SLOTOCOUP SF 50 can also be applied for the production of thermal bars with high heat dissipation. So the process becomes applicable for Panel Plating (Tending and/or Subtractive Process) as well as for pattern plating.

The deposited layers are characterized despite of pattern plating becoming more and more complicated by a very good and homogeneous metal distribution. By controlling the current density and electrolyte composition the metal distribution can be further adapted to the geometrical conditions of the PCBs to be plated.

The layers deposited from Copper SLOTOCOUP SF 50 are very bright with a brilliant levelling and excellent metal distribution. This electrolyte has been especially developed for the use in vertical reel-to-reel plating lines.

Copper SLOTOCOUP SF 50 is made-up with three liquid additives.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

